

ABSTRACT

The present invention is a slicing method and a wire saw apparatus including winding a wire around a plurality of grooved rollers and pressing the wire against an ingot to be sliced into wafers while supplying a slurry for slicing to the grooved rollers and causing the wire to travel in a reciprocating direction, in which the ingot is sliced with controlling a temperature of the ingot by supplying a slurry for adjusting an ingot temperature to the ingot independently from the slurry for slicing while the slurry for adjusting an ingot temperature is supplied to the ingot only at the exit side of the wire caused to travel in the reciprocating direction. As a result, there is provided a method and a wire saw apparatus in which rapid cooling of an ingot especially in a time close to end of slicing of the ingot can be alleviated, consequently degradation of a nano-topography can be suppressed, and further high-quality wafers having a uniform thickness can be sliced when slicing the ingot by using a wire saw.